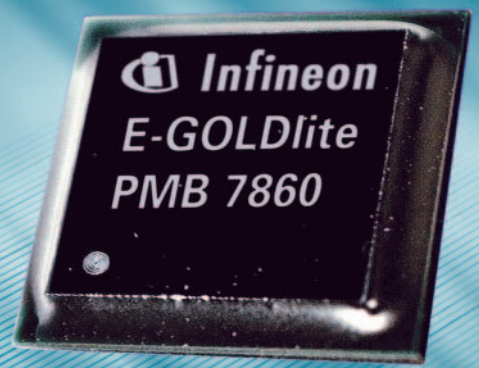




PMB 7860

E-GOLDlite

Lowest Cost GSM/GPRS/Baseband IC

E-GOLDlite is a very cost optimised and compact integrated mixed signal baseband IC for complete GSM/GPRS modems. Its flexible systems architecture fits at best to future entry level phones with GPRS and basic MMS functionality. In conjunction with Infineon's single chip CMOS RF-transceiver SMARTi SD and the power management IC E-POWERlite the single chip IC E-GOLDlite reaches best-in-class system costs.

Applications

- Future GSM/GPRS entry level phones with basic MMS functionality and cost optimised highly integrated modems and data modules

Features

- Supports a wide variety of RF architectures
- 1.5 V design in 0.13 μ drawn C11-technology
- Microcontroller C166s CPU with 52 MHz
- DSP TEAKLite® with 104 MHz
- All Interfaces required for scalable systems (ASCs, I²Cs, I²Ss, ISSs)
- Voice memo and voice activity detection
- Echo cancellation for handsfree
- CSD up to 14.4 kbit/s, HSCD class 4
- GPRS CS1 to CS4, up to class 10
- Speech codecs HR, FR, EFR and AMR
- E-OTD and TTY support
- Integrated Polyringer

Package

- Highest integration with Flip Chip package LF2BGA-201
- Smallest board footprint of 8x8 mm

Documentation/ Development and Support

- Product Overview
- Specification
- Mature GPRS protocol stack including Applications from COMNEON
- Complete system designs including PCB, SW and respective services
- User Manual
- Application Note
- Evaluation Board

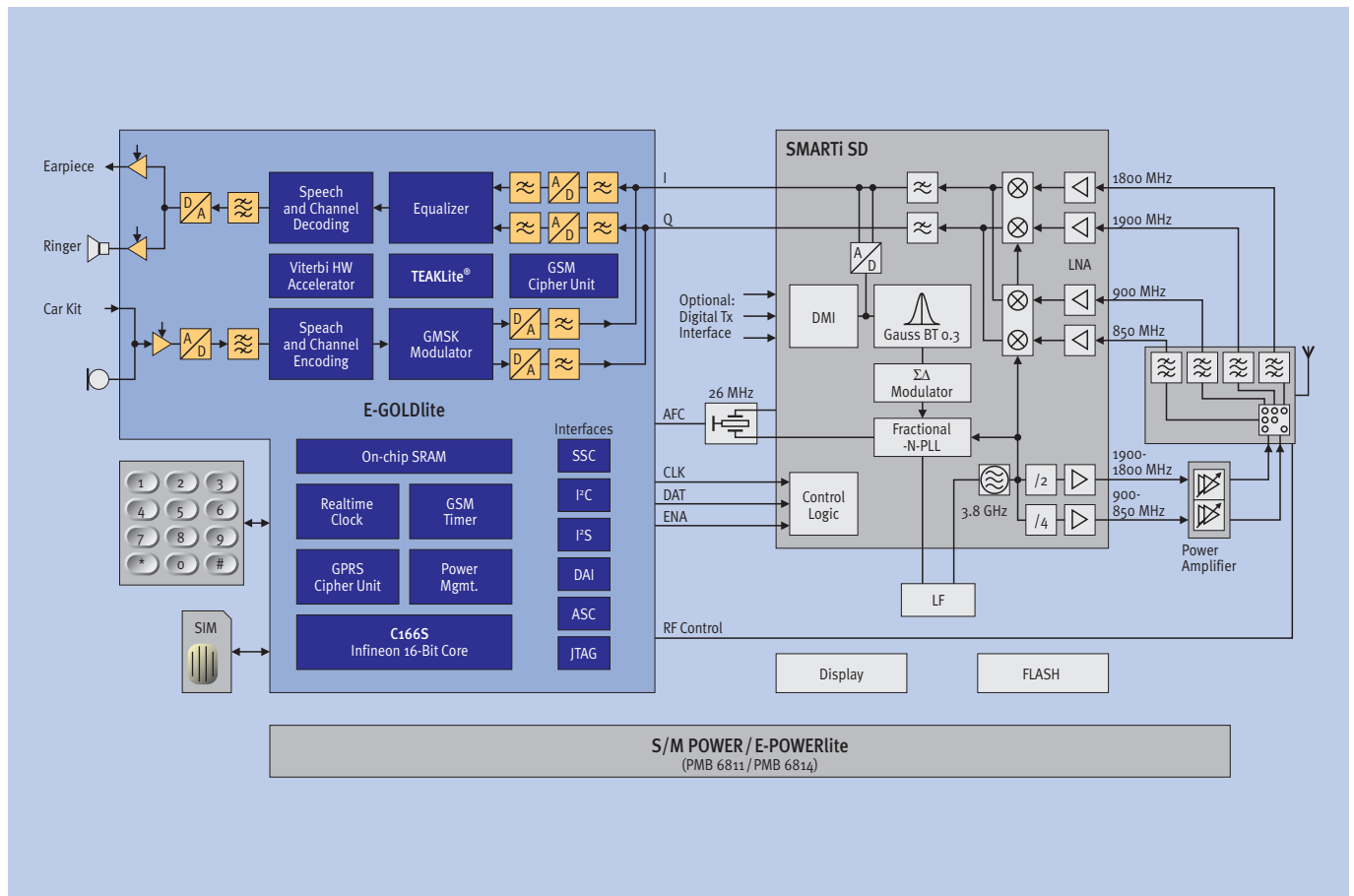
www.infineon.com/mobilesolutions

Mobile Solutions



Never stop thinking.

System Architecture with RF-Transceiver SMARTi SD and E-GOLDlite



Note: TEAKLite® is a registered trademark of ParthusCeva, Inc.

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